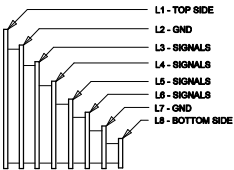


TOP SIDE SHOWN

SIZE	QTY	SYM	PLATED	TOL
0.008	448	+	YES	+/-0.003
0.01	676	□	YES	+/-0.003
0.035	13	◇	YES	+/-0.003
0.055	10	+	YES	+/-0.003
0.07	3	X	NO	+/-0.003
0.095	22	X	YES	+/-0.003
0.187	10	+	NO	+/-0.003
0.215	4	X	YES	+/-0.003

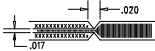
REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	2	PRODUCTION	HZ 06-01-22



LAYER CONSTRUCTION

NOTES: UNLESS OTHERWISE SPECIFIED

- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR OR EQUIVALENT.  
-FINISHED THICKNESS TO BE 0.002 +/- .005  
-TOTAL OF 8 LAYERS WITH 2 OZ. CU EXTERNAL LAYERS AND 1 OZ. CU ON ALL INTERNAL LAYERS  
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.  
0/0 ARE PRIMARY DATUMS.
- DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001 THICK MIN.  
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.  
-HOLE LOCATION TOLERANCES ARE +/-0.003 IN RELATION TO CENTER
- FINISH: -SMDRC USING LP BOTH SIDES, COLOR GREEN.  
-GOLD IMMERSION BOTH SIDES.  
-FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.  
7. DESIGN HAS SOLDER MASK DEFINED PADS ON U1-U4.  
U1-U4 SOLDER MASK SIZE IS 25 MIL AND PAD SIZE IS 29 MIL.  
DON'T CHANGE PAD SIZE OR SOLDER MASK SIZE.
- PCBS ARE TO BE RoHS COMPLIANT.
- SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):



- PLUG ALL VIA'S WITH NON-CONDUCTIVE EPOXY AND PLATE OVER PLANARIZE FINAL SURFACE.

UNLESS OTHERWISE SPECIFIED		APPROVALS		ANALOG DEVICES	
DIMENSIONS ARE IN INCHES		PCB DES.	AN	TITLE: FABRICATION DRAWING HIGH EFFICIENCY, POLYPHASE, HYBRID STEP-DOWN $\mu$ MODULE BUS CONVERTER	
TOLERANCES:		APP. ENG.	HZ		
0.0XX = ± 0.01				SIZE IC NO. LTM4660Y	
0.0XXX = ± 0.005				DC2959A(A,B,C)	
INTERPRET DIM AND TOL PER ASME Y14.5M-1994				REV	
THIRD ANGLE PROJECTION				2	
		SCALE = NONE		FILENAME: DC2959A-2.PCB	
				SHT 1 OF 1	